TOSHIBA Photocoupler GaAlAs Ired & Photo-IC

TLP2200

Isolated Bus Driver
High Speed Line Receiver
Microprocessor System Interfaces
MOS FET Gate Driver
Direct Replacement for HCPL-2200

The TOSHIBA TLP2200 consists of a GaA ℓ As light emitting diode and integrated high gain, high speed photodetector. This unit is 8–lead DIP package.

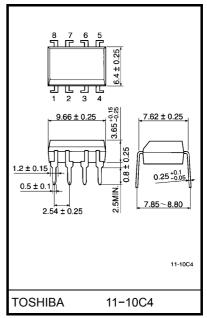
The detector has a three state output stage that eliminates the need for pull–up resistor, and built–in Schmitt trigger. The detector IC has an internal shield that provides a guaranteed common mode transient immunity of $1000V\,/\,\mu s.$

- Input current: I_F = 1.6 mA
- Power supply voltage: V_{CC} = 4.5~20 V
- Switching speed: 2.5MBd guaranteed
- Common mode transient immunity: ±1000V / us (min)
- Guaranteed performance over temperature: 0~85°C
- Isolation voltage: 2500 Vrms (min)
- UL recognized: UL1577, file No. E67349

Truth Table (positive logic)

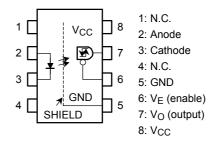
Input	Enable	Output
Н	Н	Z
L	Н	Z
Н	L	Н
L	L	L

Unit: mm

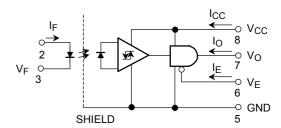


Weight: 0.54 g (typ.)

Pin Configuration (top view)



Schematic



Recommended Operating Conditions

Characteristic	Symbol	Min	Тур.	Max	Unit
Input current, on	I _{F(ON)}	1.6	-	5	mA
Input current, off	I _{F(OFF)}	0	1	0.1	mA
Supply voltage	V _{CC}	4.5	ı	20	٧
Enable voltage high	V _{EH}	2.0	1	20	V
Enable voltage low	V _{EL}	0	_	0.8	V
Fan out (TTL load)	N	_		4	_
Operating temperature	T _{opr}	0	_	85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Absolute Maximum Ratings (no derating required up to 70°C)

	Characteristic		Symbol	Rating	Unit
٥	Forward current		lF	10	mA
Ш	Peak transient forward current (Note 1)	I _{FPT}	1	Α
_	Reverse voltage		V_{R}	5	V
٦	Output current		lo	25	mA
c t o	Supply voltage		V_{CC}	-0.5~20	V
Φ	Output voltage		Vo	-0.5~20	V
e t	Three state enable voltage		VE	-0.5~20	V
	Total package power dissipation (Note 2)	PT	210	mW
Оре	rating temperature range		T _{opr}	-40~85	°C
Stor	age temperature range	T _{stg}	-55~125	°C	
Lead	d solder temperature (10s) (**)	T _{sol}	260	°C	
	ation voltage 1minute, R.H. ≤ 60%,Ta = 25°C) (BVS	2500	Vrms	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- (Note 1) Pulse width 1µs, 300 pps.
- (Note 2) Derate 4.5mW / °C above 70°C ambient temperature.
- (Note 3) Device considered a two terminal device: Pins 1, 2, 3 and 4 shorted together, and pins 5,6,7 and 8 shorted together
 - (**) 1.6mm below seating plane.

Electrical Characteristics (unless otherwise specified, Ta = 0~85°C, V_{CC} = 4.5~20V, $I_{F(ON)}$ = 1.6~5mA, $I_{F(OFF)}$ = 0~0.1mA, V_{EL} = 0~0.8V, V_{EH} = 2.0~20V)

Characteristic	Symbol	Test Condition		Min	Тур.*	Max	Unit
Output leakage current		I _F = 5mA,	V _O = 5.5V	_	_	100	
(V _O > V _{CC})	Іонн	V _{CC} = 4.5V	V _O = 20V	_	2	500	μΑ
Logic low output voltage	V _{OL}	I _{OL} = 6.4mA (4 TT	TL load)	_	0.32	0.5	V
Logic high output voltage	V_{OH}	I _{OH} = -2.6mA		2.4	3.4	_	>
Logic low enable current	I _{EL}	V _E = 0.4V		_	-0.13	-0.32	mA
		V _E = 2.7V			_	20	
Logic high enable current	I _{EH}	V _E = 5.5V		_	_	100	μΑ
		V _E = 20V		_	0.01	250	
Logic low enable voltage	V _{EL}	_	_	_	_	0.8	V
Logic high enable voltage	V _{EH}	_	_	2.0	_	_	V
Logic low supply current	I _{CCL}	I _F = 0mA	V _{CC} = 5.5V		5	6.0	A
Logic low supply current	ICCL	V _E = don't care	V _{CC} = 20V		5.6	7.5	mA
Logic high supply current	loou	I _F = 5mA	V _{CC} = 5.5V	_	2.5	4.5	- mA
Logic High supply current	ICCH	V _E = don't care	V _{CC} = 20V	_	2.8	6.0	
	I _{OZL}	$I_F = 5mA$ $V_E = 2V$	V _O = 0.4V	_	1	-20	
High impedance state	lozh	I _F = 0mA V _E = 2V	V _O = 2.4V	_	1	20	μА
output current			V _O = 5.5V	_	1	100	
			V _O = 20V	_	0.01	500	
Logic low short circuit	la a	I _F = 0mA	$V_O = V_{CC} = 5.5V$	25	55	_	mA
output current (Note 4)	losL	IF - OHA	V _O = V _{CC} = 20V	40	80	_	ША
Logic high short circuit	loou	I _F = 5mA	V _{CC} = 5.5V	-10	-25	_	mA
output current (Note 4)	out current (Note 4)		V _{CC} = 20V	-25	-60	_	ША
Input current hysteresis	I _{HYS}	V _{CC} = 5V		_	0.05	_	mA
Input forward voltage	V _F	I _F = 5mA, Ta = 25°C		_	1.55	1.7	V
Temperature coefficient of forward voltage	ΔV _F / ΔTa	I _F = 5mA		_	-2.0	_	mV / °C
Input reverse breakdown voltage	BV _R	I _R = 10μA, Ta = 25°C		5	_	_	V
Input capacitance	C _{IN}	V _F = 0V, f = 1MHz, Ta = 25°C			45	_	pF
Resistance (input-output)	R _{I-O}	V _{I-O} = 500V R.H. ≤ 60% (Note 3)		5×10 ¹⁰	10 ¹⁴	_	Ω
Capacitance (input-output)	C _{I–O}	V _{I-O} = 0V, f = 1M	_	0.6	_	pF	

^(**) All typ. values are at Ta = 25°C, V_{CC} = 5V, $I_{F(ON)}$ = 3mA unless otherwise specified.

Switching Characteristics (unless otherwise specified, Ta = $0~85^{\circ}$ C, $V_{CC} = 4.5~20$ V, $I_{F(ON)} = 1.6~5$ mA, $I_{F(OFF)} = 0~0.1$ mA)

Characteristic		Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Propagation delay time to logic high output level		$t_{\sf pLH}$		Without peaking capacitor C ₁	-	235	1	ns
	(Note 5)	•		With peaking capacitor C ₁	_	1	400	
Propagation delay time to logic low output level		t _{pHL}	1	Without peaking capacitor C ₁		250	1	ns
	(Note 5)	•		With peaking capacitor C ₁	_		400	
Output rise time (10-90%)		t _r			_	35	1	ns
Output fall time (90–10%)		t _f		_	_	20	1	ns
Output enable time to logic high		t _{pZH}		_	_	-	-	ns
Output enable time to logic low		t _{pZL}		_	_	_	_	ns
Output disable time from logic high		t _{pHZ}	2	_	_	_	_	ns
Output disable time from logic low		t _{pLZ}		_		1	1	ns
Common mode transient immunity at logic high output	(Note 6)	CM _H		I _F = 1.6mA, V _{CM} = 50V, Ta = 25°C	-1000	-	-	V / µs
Common mode transient immunity at logic low output	(Note 6)	CML	3	I _F = 0mA, V _{CM} = 50V, Ta = 25°C	1000	_	_	V / µs

^(*) All typ. values are at Ta = 25°C, V_{CC} = 5V, I_{F(ON)} = 3mA unless otherwise specified.

- (Note 4) Duration of output short circuit time should not exceed 10ms.
- (Note 5) The t_{pLH} propagation delay is measured from the 50% point on the leading edge of the input pulse to the 1.3V point on the leading edge of the output pulse.

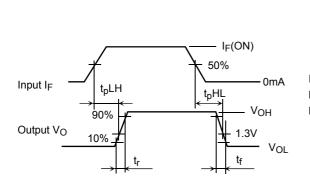
The t_{pHL} propagation delay is measured from the 50% point on the trailing edge of the input pulse to the 1.3V point on the trailing edge of the output pulse.

(Note 6) CM_L is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic low state ($V_O \le 0.8V$).

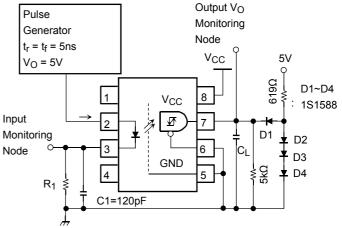
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 CM_H is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic high state ($V_O \le 2.0V$).

Test Circuit 1 t_{pHL} , t_{pLH} , t_r and t_f



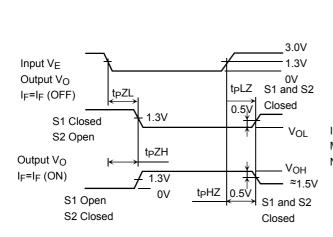
R ₁	2.15kΩ	1.1kΩ	681Ω
I _F (ON)	1.6mA	3mA	5mA

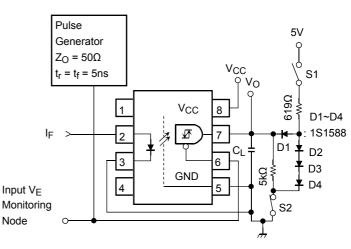


 ${\sf C}_1$ is peaking capacitor. The probe and jig capacitances are included in ${\sf C}_1$. ${\sf C}_L$ is approximately 15pF which includes probe

and stray wiring capacitance.

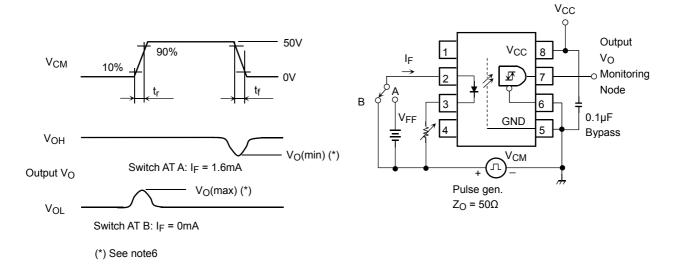
Test Circuit 2 t_{pHZ}, t_{pZH}, t_{pLZ} and t_{pZL}





 $\ensuremath{\text{C}_{\text{L}}}$ is approximately 15pF which includes probe and stray wiring capacitance.

Test Circuit 3 Common Mode Transient Immunity



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